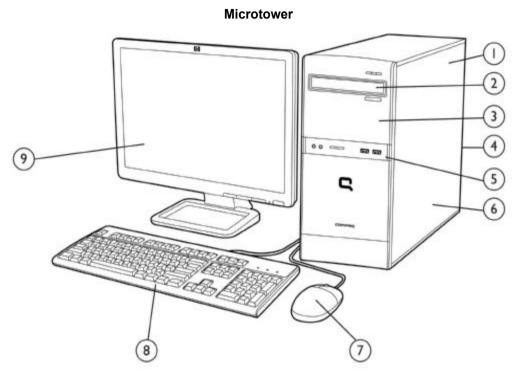
Overview

Windows®. Life without Walls™. HP recommends Windows 7.



- 1. 300-watt power supply
- 2. (1) external 5.25-inch bay for optional optical drive
- 3. (1) internal 3.5-inch bay for hard disk drive
- 4. Rear I/O includes (4) USB 2.0 ports, RJ-45 network port, VGA video port, audio in/out jacks, microphone jack
- 5. Front I/O includes (2) USB 2.0 ports, audio in/out jacks, Media Card Reader (select countries/models only)
- Full height expansion slots include (1) PCI 2.3 slot,
 PCIe x1 slots, (1) PCIe x16 graphics slot
- 7. Compaq USB Optical Scroll Mouse
- 8. Compaq USB Standard Keyboard
- 9. Monitor (sold separately)

Overview

At A Glance

- Intel® Core™ 2 Quad and Core™ 2 Duo processors, Intel Pentium® processors, or Intel Celeron® processors
- · Choice of operating systems:
 - O Genuine Windows 7 Professional Edition 32
 - Windows XP Professional (available through downgrade rights from Genuine Windows 7 Professional)
 - O Genuine Windows 7 Home Premium Edition 32
 - O Genuine Windows 7 Home Basic Edition 32
 - Genuine Windows 7 Starter
 - O Genuine Windows Vista Home Basic
 - O Novell SUSE Linux Enterprise Desktop 11
 - o FreeDOS
- Intel G41 Express Chipset
- Intel I/O Controller Hub 7 (ICH7)
- DDR3 SDRAM PC3-10600 (1066/1333 MHz) non-ECC system memory
- Intel Graphics Media Accelerator 4500
- PCI and PCI Express I/O buses
- Serial ATA controller
- USB 2.0 support
- Realtek RTL8103EL 10/100 Fast Ethernet controller
- Choice of hard drives and optical drives
- Protected by HP Services. Terms and conditions vary by country. Certain restrictions and exclusions apply.



Standard Features and Configurable Components (availability may vary by country)

Processor and Speed

ed Intel Celeron Processors

One of the following

Intel Celeron 440 Processor (2.00 GHz, 512-KB L2 cache, 800 MHz FSB) Intel Celeron 450 Processor (2.2 GHz, 512K L2 cache, 800 MHz FSB)

Intel Celeron Dual-Core Processors

Intel Celeron E1500 Processor (2.2 GHz, 512K L2 cache, 800 MHz FSB) Intel Celeron E1600 Processor (2.4 GHz, 512K L2 cache, 800 MHz FSB) Intel Celeron E3200 Processor (2.4 GHz, 1MB L2 cache, 800 MHz FSB) Intel Celeron E3300 Processor (2.5 GHz, 1MB L2 cache, 800 MHz FSB)

Intel Pentium Dual-Core Processors

Intel Pentium E5300 Processor (2.6 GHz, 2MB L2 cache, 800 MHz FSB)
Intel Pentium E5400 Processor (2.70 GHz, 2MB L2 cache, 800 MHz FSB)
Intel Pentium E6300 Processor (2.80 GHz, 2MB L2 cache, 1066 MHz FSB)
Intel Pentium E6500 Processor (2.93 GHz, 2MB L2 cache, 1066 MHz FSB)

Intel Core 2 Duo Processors

Intel Core 2 Duo E7500 Processor (2.93 GHz, 3 MB L2 cache, 1066 MHz FSB)

Intel Core 2 Quad Processors

Intel Core 2 Quad Q8300 processor (2.50 GHz, 4 MB L2 cache, 1333 MHz FSB)

NOTE: Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families.

Operating Systems and Preinstalled

Application Software

(availability varies by region)

Genuine Windows 7 Professional Edition 32*

Windows XP Professional (available through downgrade rights

from Genuine Windows 7 Professional)*+
Genuine Windows 7 Home Premium Edition 32*
Genuine Windows 7 Home Basic Edition 32*

Genuine Windows 7 Starter*

Genuine Windows Vista Home Basic**
Novell SUSE Linux Enterprise Desktop 11

FreeDOS

SupportedGenuine Windows Vista Business 32**CertifiedNovell SUSE Linux Enterprise Desktop 11

Microsoft Office 2007 Basic

Microsoft Office 2007 Small Business

Microsoft Office 2007 Professional

HP Power Manager 2.0

Roxio Creator Business 10 HD++



^{*} System may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See: http://www.microsoft.com/windows/windows-7/ for details.

^{**} Certain Windows Vista product features require advanced or additional hardware. See: http://www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and http://www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor.

⁺ Windows 7 Professional disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custon image.

Standard Features and Configurable Components (availability may vary by country)

Corel WinDVD Player++

McAfee Total Protection Anti-Virus with 60 day trial Subscription

PDF Complete

HP Total Care Advisor

++ Supporting software available with certain optical drive configurations

Hard Drives

160-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm) 250-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm) 320-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm) 500-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm)

System Memory

1-GB DDR3 Synch DRAM PC3-10600 (1066/1333-MHz) Non-ECC (1 x 1GB)
2-GB DDR3 Synch DRAM PC3-10600 (1066/1333-MHz) Non-ECC (2 x 1GB)
2-GB DDR3 Synch DRAM PC3-10600 (1066/1333-MHz) Non-ECC (1 x 2GB)
3-GB DDR3 Synch DRAM PC3-10600 (1066/1333-MHz) Non-ECC (1 x 2GB, 1x1GB)

4-GB DDR3 Synch DRAM PC3-10600 (1066/1333-MHz) Non-ECC (2 x 2GB) **NOTE**: Memory runs at maximum system supported speed of 1066 MHz.

Storage -

One or more of the following (see Storage section below)

Media Reader (select countries/models only)

HP 6-in-1 Media Card Reader (part of front I/O assembly)

Optical Drives (Serial ATA)

SATA DVD-ROM Drive

SATA SuperMulti LightScribe DVD Writer Drive

Input Devices

Keyboard

Compaq USB Standard Keyboard HP Mini USB Keyboard (optional)

Mouse

Compaq USB Optical Scroll Mouse

Audio

Realtek ALC662 High Definition audio codec 3D audio compliant and HD Audio compatible HD LISP. This Deverad Speakers.

HP USB Thin Powered Speakers

Communication

Integrated Realtek RTL8103EL 10/100 Ethernet Controller

Intel Gigabit CT Desktop NIC (optional)

LSI PCIe x1 Hi-Speed 56K International SoftModem (optional)

HP PCIe Wireless 802.11b/g/n

Graphics

Integrated Intel Graphics Media Accelerator 4500 NVIDIA GeForce G210 HDMI PCIe x16 Graphics Card ATI Radeon HD 4350 HDMI PCIe x16 Graphics Card



Standard Features and Configurable Components (availability may vary by country)

Miscellaneous HP FireWire / IEEE 1394 PCI Card (full height)

HP Serial/Parallel PCI Card (full height)



System Details

Base Unit

- Micro ATX microtower chassis, including power supply and front bezel
- Two (2) drive bays and four expansion slots
- Microsoft operating system CD optional
- Active type heatsink
- 92 x 92 x 25 mm chassis fan
- System board with Intel G41 Express chipset, Intel I/O Controller Hub 7 (ICH7), Realtek RTL8103EL 10/100 Ethernet controller, Intel GMA graphics, and Realtek audio, (1) fullheight PCI 2.3 slot, (2) PCI Express x1 slots, (1) PCI Express x16 slot, (2) DDR3 DIMM memory slots. (4) Serial ATA data connectors
- Product documentation on CD
- HP system restore CD optional

Power cord

Slots

PCI One (1) full-height PCI 2.3 slot

Two (2) full-height PCI Express x1 slots

One (1) full-height PCI Express x16 slot (for graphic cards)

Two (2) DDR3 SDRAM DIMM slots (4 GB maximum memory support) **Memory Expansion**

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all

memory may not be available due to system resource requirements.

Bays

Internal

One (1) 3.5"

External

One (1) 5.25"

USB Support

EHCI high-speed USB 2.0 controller

Two (2) front ports; Four (4) rear ports, Two (2) internal ports on system board

Interfaces (Legacy)

One (1) analog VGA video port

One (1) line in; one (1) line out; one (1) mic in

One (1) RJ45 network port

Weight & Dimensions

Chassis Dimensions $(H \times W \times D)$

15.11 x 6.54 x 16.87 in

Packaged Dimensions 23.03 x 19.61 x 9.65 in

384 x 166 x 428 mm

 $(L \times W \times H)$

585 x 498 x 245 mm

System Weight

Shipping Weight

22.4 lb (10.2 kg) 30.8 lb (14.0 kg)

Technology and

Features

PC3-10600 DDR3 SDRAM (1066/1333MHz) non-ECC **Memory Type**

Up to 4-GB maximum system memory supported

NOTE: Memory runs at maximum system supported speed of 1066 MHz. For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available

due to system resource requirements. **Hard Drive Interfaces**

Serial ATA

Supported



Chassis **Front Panel** Power button

> Power On LED **HDD Activity LED**

Cooling Solutions

Power Supply Fan (variable speed) **Supported** Active heatsink (variable speed)

Chassis fan

Slots Supported Four (4) full-height expansion slots

Front I/O Two (2) USB 2.0 ports

Rear I/O Standard Micro ATX I/O connectors, including four (4) USB 2.0 ports

Drive Bays One (1) 5-1/4" external

One (1) 3-1/2" internal

Internal Speaker N/A

Security Padlock loop

Kensington Lock Support

Support for chassis padlocks and cable lock devices

Power Supply 300-watt ATX Power Supply - PFC/non-PFC with a 115v/230v line

switch (varies by country/region)

Unit Environment and Operating Conditions

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 4 in (10.2 cm) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating 50° to 95° F (10° to 35° C)

> Non-operating -22° to 140° F (-30° to 60° C)

Operating **Relative Humidity** 10% to 90% (non-condensing at ambient)

> Non-operating 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating 10,000 ft (3048 m) (unpressurized) Non-operating 30,000 ft (9000 m)

NOTE: Operating temperature is de-rated 1.0 deg C per 1000 ft (300 m) to 10,000 ft (3000 m) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



System Board

Processor Socket T; LGA775 industry standard Micro ATX form factor

Supports Intel Core 2 Quad and Core 2 Duo processors, Intel Pentium

processors, Intel Celeron processors

PWM ISL6312 – 3 Phase Chipset Intel G41 Express

Intel I/O Controller Hub 7 (ICH7)

Super I/O Fintek F71882FG
Front Side Bus 800/1066/1333 MHz

Frequency

Memory DDR3 SDRAM

2 x DIMM slots

Clock Generator SLG505YC26481

Integrated Graphics Intel Graphics Media Accelerator (GMA)

Audio Realtek ALC662 HD Audio compatible codec with two channel audio 3D

audio

LOM Realtek RTL8103EL 10/100 Fast Ethernet controller

Storage Four Serial ATA interfaces (hard drive and optical drive)

Expansion Slots 1 x PCl 2.3 slot

2 x PCI Express x1 slots 1 x PCI Express x16 slot

BIOS SPI EEPROM Industrial Standard PCI 2.3 compliant

USB 2.0

Rear Side I/O Ports 4 x USB 2.0 ports

1 x RJ-45 10/100 port

1 x D-sub 15 pin analog VGA port

3 x audio ports

On Board I/O Interfaces 1 x ATX power connector

1 x +12V power connector

1 x Front panel connector, Switch, LED (ON/Flash/OFF)

2 x Fan headers for CPU, chassis, with voltage/fan speed control

1 x header to support 2 USB 2.0 ports at front side

1 x header to support 2 front (Headphone/Mic) audio ports

1 x header to support USB media reader

Board Size Micro-ATX, PCB Size: 9.6 x 9.6 in (24.38 x 24.38 cm)

4-layer PCB with green color

Additional Features

· Bootable without keyboard, mouse or monitor

Keyboard/mouse/USB wake up

Support S3, S4 and S5

ACPI status

Hardware monitor capability

CPU fan speed control

Network Interface

Integrated Realtek RTL8103EL 10/100 Fast Features **Ethernet Controller**

Hardware Highlights

PCIe x1 interface

10-Mbps and 100-Mbps operation Crossover detection and auto-correction Wake-on-Lan and remote Wake-up (Wakeon-LAN supported from S3, S4 only. Not

supported from S5)

Intel Gigabit CT Desktop NIC

Hardware Highlights

Features

PCI Express interface 10-Mbps, 100-Mbps and 1000-Mbps

operation (Wake-on-LAN supported from S3,

S4 only. Not supported from S5)

Wireless

Wireless 802.11b/g/n PCIe Card (full height bracket)

Power Supply

- ATX Power Supply Passive PFC/non-PFC with a 115v/230v line switch
- Passive Power Factor Correction (PFC) with line switch set to 230V No PFC in 115V line switch position
- 90 to 140VAC, or 180 to 264VAC operating voltage range
- 100 to 127VAC, or 200 to 240VAC rated voltage range
- 50-60 Hz rated line frequency
- 47-63 Hz operating line frequency range
- 300 watt maximum rated power
- 80-mm power supply fan variable speed for optimum acoustics

Power Conservation 'Energy Saver'

- APM 1.2 support
- Screen blanking
- Hard drive 'Idle' mode
- System Idle mode
- ~2 watt power consumption in ES mode suspend to RAM (S3) (instantly available PC)
- Processor/Cache memory power-down (S3)
- Eup Lot 6 less than 1W with BIOS setup option (Max power savings)

System Environmental Specs

- Values are subject to change without notification and are for reference only.
- Performance of system, options, and ancillary equipment will vary depending on the system configuration.
- Levels presented do not account for non-HP/Compag installed hardware.

Ambient Air Temperature	Operating	50° to 95°F (10° to 35°C) at sea level with an altitude de-rating of 1.0°C per every 1000 ft (300 m) above sea level to a maximum of 8000 ft (2500 m), no direct sustained sunlight. Maximum rate of change is 77°F/Hr (25°C/Hr). The upper limit may be limited by the type and number of options installed.
	Storage	–22° to 140°F (–30° to 60°C) – Maximum rate of change: 410°F/Hr (210°C/Hr).
Humidity	Operating	10% to 90% relative humidity (Rh), 86°F (30°C) maximum wet bulb temperature, noncondensing
	Storage	10% to 95% relative humidity (Rh), 101.66°F (38.7°C) maximum wet bulb temperature, non-condensing
Altitude	Operating	0 to 10,000 feet (0 to 3048 meters) – This



value may be limited by the type and number of options installed. Maximum allowable altitude change rate is 1,000 ft/min (304.8

m/min).

Non-Operating 0 to 30,000 feet (0 to 9,144 meters) –

Maximum allowable altitude change rate is

1200 ft/min (365.76 m/min).

Shock Listed are the levels of shock the product can withstand with NO

damage being incurred. The values represent peak input acceleration during a 2 to 3 ms half-sine shock pulse, 11 ms trapezoidal shock pulse

Non-Operating 35G's (Half-sine Shock)

35G's (Trapezoidal Shock)

Vibration Listed are the levels of vibration the product can withstand with NO

Operating

damage being incurred. The values represent a flat random vibration

input acceleration profile across the given frequency range.

Random vibration at 5Hz@0.00025G²/Hz, 10Hz@0.01G²/Hz, 100Hz@0.01G²/Hz,

300Hz@0.00001G2/Hz

5Hz to 300Hz, (0.25G's nominal).

Non-Operating Random vibration at 0.008G²/Hz,

10Hz to 500Hz, (2 Grms nominal).

Service and Support

On-site Warranty^{Note 1}: One-year (1-1-1) limited warranty delivers one year of on-site, next business-day^{Note 2} service for parts and labor and includes free telephone support^{Note 3} 24 x 7. Global coverage^{Note 2} ensures that any product purchased in one country and transferred to another non-restricted country will remain fully covered under the original warranty and service offering. One-year onsite and labor are not available in all countries.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured Compaq and third-party HP-qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.



After-Market Options (availability may vary by country)

Communications	NICs	
	Intel Gigabit CT Desktop NIC	FH969AA
	Wireless LAN	
	HP Wireless 802.11 b/g/n PCle Card	FH971AA
	Modems	EU07044
	LSI PCIe x1 Hi-Speed 56K International SoftModem	FH970AA
	HP RJ11 Modem Adapter Kit	DC131C
Hard Disk Drives	HP 500-GB SATA 3.0-Gb/s Hard Drive	KW347AA
	HP 320-GB SATA 3.0-Gb/s Hard Drive	FH963AA
	HP 250-GB SATA 3.0-Gb/s Hard Drive	PY278AA
	HP 160-GB SATA 3.0-Gb/s Hard Drive	PY277AA
Input Devices	Compaq Standard USB Keyboard	TBD
•	HP Mini USB Keyboard	AS601AA
	Compaq Optical Scroll USB Mouse	TBD
Memory	HP 2-GB PC3-10600 (DDR3-1333 MHz) DIMM	AT024AA
	HP 1-GB PC3-10600 (DDR3-1333 MHz) DIMM	AT023AA
Audio	HP USB Thin Powered Speakers	KK912AA
Graphics	NVIDIA GeForce G210 HDMI PCIe x16 Card	TBD
•	ATI Radeon HD 4350 HDMI PCIe x16 Graphics Card	TBD
Optical Drives	HP SATA DVD-ROM Drive	AH047AA
	HP SATA SuperMulti LightScribe DVD Writer Drive	GF343AA
Security	HP Business PC Security Lock Kit	PV606AA
	HP Security Cable with Kensington Lock	PC766A
Miscellaneous	HP FireWire / IEEE 1394 PCI Card	PA997A
Accessories	Belkin USB To Serial Adapter	EM449AA
	HP Serial/Parallel PCI Card	KD062AA
Monitors*	Compaq CQ1859s 18.5-inch LCD Monitor	TBD
	HP LE1851w 18.5-inch Widescreen LCD Monitor	TBD
	*This is only representative, not an exhaustive list. All HP monitors are	
	supported that accept a graphics output provided by this PC.	



Memory

DDR SYNCH DRAM NON-ECC MEMORY

The Intel G41 Express chipset supports non-ECC DDR3 memory up to PC3-10600 (1333 MHz). However, the chipset runs this memory at a maximum clock rate of 1066 MHz. Memory upgrades are accomplished by adding single or dual DIMMs of the same or varied sizes. This chart does not represent all possible memory configurations.

CAUTION: You must shut down the computer **and disconnect the power cord** before adding or removing memory modules Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

HP recommends dual-channel symmetric configurations for maximum performance.

For best performance, add the same amount of total memory to each channel and do not mix speeds. For dual-channel symmetric performance, the total amount of memory in each channel must be equal. If speeds are mixed, speed will default to the slowest DIMM.

STANDARD MEMORY

1-GB, 2-GB, 3-GB or 4-GB DDR3 SYNCH DRAM

OPTIONAL MEMORY UPGRADES

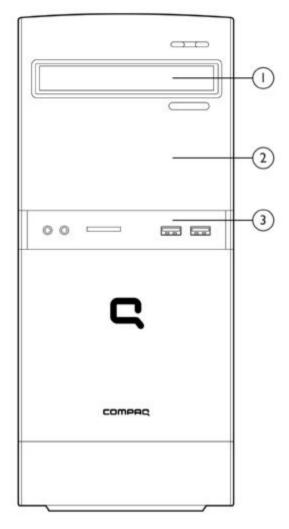
Supports up to 4 GB of DDR3 SYNCH DRAM. Not all memory configurations possible are represented below.

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

DIMM Size	Slot 1	Slot 2
1-GB	1-GB	
2-GB (dual-channel symmetric)	1-GB	1-GB
3-GB	1-GB	2-GB
3-GB	2-GB	1-GB
4-GB (dual-channel symmetric)	2-GB	2-GB



Storage



Compaq 500B Microtower PC

	Maximum Quantity Supported	Position Supported	Controller
Optical Drive	1	1	SATA
3.5" Serial ATA Hard Drive	1	2	SATA
Media Reader (select countries/models only)	1	3	Internal USB 2.0 port

Technical Specifications - Audio

Integrated Realtek ALC662 Audio

Type Integrated HD Audio compatible Yes

codec 5:1 channel

Sampling Supports 48/96 KHz

Audio Jacks Mic-In

Line-In

Line-Out / Headphone Out

Power Support Digital: 3.3V

Analog: 5V

Other Meets performance requirements for audio on PC99/2001 systems

High-performance DACs with 97dB SNR(A-Weighting)

ADCs with 90dB NR(A-Weighting)



Technical Specifications - Communications

Integrated Realtek RTL8103EL 10/100 Fast Ethernet Controller

Controller 8101E Memory N/A

Data rates supported2.5GHz data rate with X1 link widthComplianceIEEE802.3, IEEE 802.3u, IEEE 802.3ab

Bus architecture PClexpress 1.1

Data transfer mode Half/Full Duplex Operation

Hardware certifications MS NDIS5, IPv4, Ipv6, TCP, UDP **Power requirement** 100mbps (heavy traffic) TBD mW

max.

10mbps (heavy traffic) TBD mW

max.

S3 with Link TBD mW
Link Down @S0 TBD mW
Link Down @S3/S5 TBD mW

Boot ROM support EEPROM, 1Kb, 2Kb **Network transfer rate** 10/100Mbps over CAT.5

10Mbps over CAT.3

Dimensions 9mm x 9mm

Management capabilities

ACPI rev 2.0, PM rev 1.1, ASPM v1.0a

Intel Gigabit CT Desktop NIC Connector RJ-45

Controller Intel WG82574L Gigabit Ethernet Controller

Memory Integrated Dual 48K configurable transmit receive FIFO Buffers

Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB and 802.3u compliant,

802.3x flow control

Bus architecture PCI-E 1.0a

Data path width X1, 250 MB/s, Bi-directional interface

Data transfer mode Bus-master DMA

Hardware certifications FCC, B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS

Mark for European Union

Power requirement Aux 3.3V, 3.0 Watts in 1000base-T and 2.0 Watts in 100Base-T

Boot ROM support Yes

Network transfer rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps

1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI Bus)

Environmental Operating temperature 32° to 131°F (0° to 55° C)

Operating humidity 85% at 131° F (55° C)

Dimensions 4.75 x 2.25 x 0.8 in (12.1 x 5.7 x 2.0 cm)

Management capabilities

WOL, PXE, DMI, WFM 2.0

HP Wireless Dimensions (L x H) 3.3 x 4.7 inches (8.5 x 12 cm)



Technical Specifications - Communications

8	02	.1	1b	/q/n	PCIe

Weight 0.08 pounds (40 g) Controller Ralink RT2790 **System interface** PCIExpress x1 **Network standard** 802.11 b/g/n Frequency band 2.400 - 2.497 GHz

Operating temperature 14° to 149°F, operating (-10° to 65°C, operating)

Storage temperature -40° to 176°F, non-operating (-40° to 80°C, non-operating)

Humidity 10-90% operating

5-95% non-operating

Operating voltage 3.3V +/- 9%

12V +/- 8%

Power consumption Platform/WLAN Mode **Power Consumption**

> Maximum Power 10 Watts

Consumption

Transmit Only 4 Watts maximum averaged power over 1

Transmit Packet or 1000 mA peak current for 100 microseconds

Active Scanning or longer

Receive Only Mode or

Idle without IEEE PSP

mode enabled

Idle, with IEEE PSP mode enabled

Transmit Disabled (turned off in software) Platform in S3 or S4

(power removed from Low Profile PCI Express

Card)

802.11b modes +19 dBm +/- 1.0 dB

maximum

802.11g modes +17 dBm +/- 1.0 dB maximum

EWC modes +17 dBm +/- 1.0 dB maximum (total power in all transmit chains)

3 Watts maximum averaged over 1 second

1.0 Watts maximum averaged over 1 second

50 mW maximum, averaged over 1 second

5 mW maximum, averaged over 1 second

Receive sensitivity

Output power

(approximately)

Mode	Data rate	Sensitivity
802.11b	1 Mbps	-94 dBm
802.11b	11 Mbps	-85 dBm
802.11g	6 Mbps	-91 dBm
802.11g	18 Mbps	-85 dBm
802.11g	48 Mbps	-75 dBm
802.11g	54 Mbps	-72 dBm
EWC (2.4 GHz)	6.5 Mbps	-87 dBm
EWC (2.4 GHz)	54 Mbps	-82 dBm
EWC (2.4 GHz)	81 Mbps	-78 dBm
EWC (2.4 GHz)	162 Mbps	-74 dBm
EWC (2.4 GHz)	270 Mbps	-68 dBm
EWC (2.4 GHz)	300 Mbps	-64 dBm

Data transfer rate

Data Rate (MCS)

Minimum Throughput 700 kbps

1 Mbps (802.11 b) 2 Mbps (802.11 b)

1.4 Mbps



Technical Specifications - Communications

5.5 Mbps (802.11 b)	3.5 Mbps
11 Mbps (802.11 b)	5.9 Mbps
12 Mbps (802.11 g)	6 Mbps
18 Mbps (802.11 g)	9 Mbps
24 Mbps (802.11 g)	12 Mbps
36 Mbps (802.11 g)	18 Mbps
48 Mbps (802.11 g)	21 Mbps
54 Mbps (802.11 g)	22.5 Mbps
6.5 Mbps (20 MHz EWC)	4.5 Mbps
13 Mbps (20 MHz EWC)	9 Mbps
19.5 Mbps (20 MHz EWC)	13.5 Mbps
26 Mbps (20 MHz EWC)	18 Mbps
39 Mbps (20 MHz EWC)	
52 Mbps (20 MHz EWC)	•
58.5 Mbps (20 MHz	40 Mbps
EWC)	
65 Mbps (20 MHz EWC)	45 Mbps
78 Mbps (20 MHz EWC)	54 Mbps
104 Mbps (20 MHz EWC)	72 Mbps
117 Mbps (20 MHz EWC)	81 Mbps
130 Mbps (20 MHz EWC)	91 Mbps
13.5 Mbps (40 MHz EWC)	8 Mbps
27 Mbps (40 MHz EWC)	16 Mbps
40.5 Mbps (40 MHz	24 Mbps
EWC)	·
54 Mbps (40 MHz EWC)	32 Mbps
81 Mbps (40 MHz EWC)	48 Mbps
108 Mbps (40 MHz EWC)	64 Mbps
121.5 Mbps (40 MHz EWC)	72 Mbps
135 Mbps (40 MHz EWC)	81 Mbps
,	

Security

- IEEE and WiFi compliant 64 / 128 bit WEP encryption
- AES: CCM
 - 802.1x authentication
 - WPA: 802.1x. WPA-PSK and TKIP
 - WPA2 certification
 - IEEE 802.11i
 - Cisco Certified Extensions, all versions through V5

Antenna HP part number 497792-001
Certifications Wi-Fi certified

Certifications for use United States, Canada, Peru, Taiwan **by country**



Technical Specifications - Communications

LSI PCIe x1 56K International SoftModem **Data Transmission**

Technology speeds: 56,000 Kbps maximum downstream data,

controllerless

NOTE: 56 Kbps technology refers to download speeds only and requires compatible modems at server sites. Other conditions may limit modem speed. FCC limitations allow a maximum of 53 Kbps during

download transmissions.

Data Speeds (Upload only) 33,600/31,200/28,800/26,400/21,600/19,200/

16,800/14,400/12,000/9,600/7,200/4,800/2,400/1,200/300

Data Standards ITU-T V.90, ITU-T, ITU-T V.34, V.44, V.42, V.42bis21, V.32bis, Bell

212A, and Bell 103

Fax Speeds 14,400/12,000/9,600/7,200/4,800/2,400/1,200/300 b/s

Fax Mode Capabilities ITU-T T.31 class 1 FAX, V. 17, V.29, V.27ter, and V.21 Channel 2

Error Correction and Data Compression

V.44, 42bis, V.42 and MNP2-5

Power Management PC

PCI Bus Power Management Interface Specification (PCI-PM) Revision 1.2, Appendix A. D0, D3hot, and D3cold. Wake on Ring state when in D3cold. If the power management event (PME) feature is enabled in D3cold, a modem can wake the system via WAKE# (WAKEN) or

beacon. Meets PCI Express 1.1 standard.

Upgradeability Driver upgradeable for future enhancements

Video ITU-T V.80 video ready interface

Other TIA/EIA 602 standard AT command set

Integrated DTE interface with speeds of up to 115.2 Kbps, parallel

16550a UART-compatible interface

Optional ring wakeup signal

Operating Temperature 32° to 158° F (0° to 70° C)

Operating Humidity 20% to 90%, non-condensing

Power Requires a 3.3-V auxiliary power rail on PCI express bus

Uses only one PCI express load (i.e., one grant/request pair), one

shared IRQ, one electrical load

Chipset LSI SV92EX - Integrated PCI interface with 3.3-V tolerant buffers and

CardBus support

Dimensions (L X H) Complies with PCI express low profile specifications-6.7 x 2.3 in (17.0 x

5.8 cm) and supports high- and low-profile brackets

Connection Single RJ-11 connector

Other Features Digital line protection, call progress monitoring via on-board piezo

device, support for high profile and low profile brackets, PnP ID support

Safety UL recognized to UL 1950, 3rd edition (U.S. and Canada); IEC 950

(TUV, NEMKO, DEMKO, SEMKO); CE Mark, EC 950 (TUV, NEMKO,

DEMKO, SEMKO, CE mark

EMC FCC Part 15, IC ES003, EN 55022, 3rd edition, EN 55024, annex A, EN

61000-4-6, EN 61000-4-8

Telecom FCC Part 68, IC-CS-03 (Canada); Worldwide PTT approvals

Not available in Korea or the Republic of South Africa.

Other The SV92EX device is packaged in a 32-pin micro leadless chip carrier

(MLCC). The SV92EX is fully compliant with the PCI Express revision

1.1 specification. WHQL approved; ASPM compliant.



Technical Specifications - Graphics

Integrated Intel Graphics Media Accelerator (GMA) 4500

3D/2D Controller VGA Controller

Microsoft DirectX® 10 based with support for Pixel Shader 2.0

Integrated

Bus Type

PCI Express™ x16 (If an external graphics card is installed in a PCI slot, the internal graphics can be enabled or disabled using the system's BIOS setup utility. If an external graphics card is installed in the PCI

Express™ slot, the internal graphics cannot be enabled).

RAMDAC Memory Integrated, 350 MHz

Graphics memory is shared with system memory. Graphics memory usage varies depending on the amount of system memory installed and system load. 8 MB is pre-allocated for graphics use at system boot time

Additional memory is allocated for graphics use at system boot Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal

balance between graphics and system memory use.

System memory equal or greater than 512 MB

8 MB pre-allocated + 248 MB DVMT = max frame buffer of 256 MB

Controller Clock Speed 250 MHz

Overlay Planes Single overlay support with 5x3 filtering

Maximum Color Depth 32 bits/pixel

Maximum Vertical Refresh Rate

75 Hz at up to 2048 x 1536 analog, 60 Hz at up to 1920 x 1200 for flat panel, 85 Hz at up to 1400 x 1050 for digital CRT/HDTV. Varies with

mode and configuration. See table below.

Multi-display Support Support for one CRT via the motherboard's VGA connector. Support for

an additional DVI-D display via the optional DVI ADD2 card. Dual independent displays and dual synchronous (Twin or Clone mode)

displays are supported.

Graphics/Video API

Support

Microsoft DirectX® 10, DirectXVA®, VMR9, GDI/GDI+; OpenGL® 1.4.

Resolutions	Resolution	Max	Maximum Refresh Rate (Hz)		
Supported ¹		Analog Monitor	Digital	Monitor	
			Flat Panel	CRT / HDTV	
	640 x 480	75	60	85	
	800 x 600	75	60	85	
	1024 x 768	75	60	85	
	1280 x 1024	75	60	85	
	1400 x 1050	75	60	85	
	1600 x 1200	75	60	N/A	
	1920 x 1080	75	60	N/A	
	1920 x 1200	75	60	N/A	
	1920 x 1440	75	N/A	N/A	
	2048 x 1536	75	N/A	N/A	

¹ Modes listed are supported with a single active display. The supported mode list for multiple active displays is a subset of this list. Not all modes will support video playback and some supported modes may use software MC (motion compensation rather than hardware MC. Not all modes will support 3D acceleration depending on the system configuration (e.g., resolution selected, size of frame buffer, number of installed memory modules, etc.).

NOTE: Other resolutions and refresh rates may be selectable but are not recommended.

ATI Radeon HD 4350 Input/Output HDMI PCIe x16 connectors

connectors VGA and HDMI

Graphics Card Board display options Supports two displays through any combination of two of the three output

ports.

DVI



Technical Specifications - Graphics

Board configuration Specification Description

Graphics Chip RV710D2
Core clock 600 MHz
Memory clock 800 MHz

Frame buffer 256 MB DDR2, 64 bit wide

Bus type PCI Express (x16 lanes)

Maximum vertical refresh85 Hz

rate

Display support Integrated 400 MHz RAMDAC

Display max resolution 1920 x 1080 digital, 2048 x 1536 analog

ATI Radeon HD 4350 DH PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP

Resolution	Maximum Refresh Rate (Hz)		
	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	N/A	

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

Languages supported 24 languages: English, Arabic, Chinese Simplified, Chinese Traditional,

Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish,

Portuguese, Russian, Spanish, Swedish, Thai, Turkish

Maximum power 21 W

Compliance standards <u>EMC Emissions</u>:

a) FCC Part 15, Subpart B – Unintentional Radiators, Class B Computing

Devices for Home & Office Use

b) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of

measurement of radio disturbance characteristics of Information

Technology Equipment

c) Canadian Standard ICES-003 is equivalent to CISPR22

d) Taiwanese Standard BSMI

e) Japanese VCCI

f) Australian C-Tick

g) Korean (KCC)

EMC Immunity:

CISPR 24:1997/EN 55024:1998 – Information Technology Equipment – Immunity Characteristics – Limits and Methods of Measurement.



Technical Specifications - Input Devices

Compaq USB Standard Physical Keys 104, 105, 106, 107, 109 layout (depending Kevboard

characteristics upon country)

Dimensions (L x W x H) 18.14 x 1.07 x 6.02 in (46.1 x 2.74 x 15.3 cm)

Weight 1.3lb(0.6 kg) minimum

Electrical Operating voltage + 5VDC ± 5%

> **Power consumption** 50-mA maximum (with three LEDs ON)

ESD CE level 4, 12.5-kV air discharge EMI - RFI Conforms to FCC rules for a Class B

computing device

Microsoft PC 99 – 2001 Functionally compliant

Mechanical 40 available Languages

Keycaps Silm design

Switch actuation 60-g nominal peak force with tactile feedback Switch life 10 million keystrokes (using Hasco modified

tester)

Switch type Contamination-resistant switch membrane

Key-leveling N/A

mechanisms

Cable length 1.5 m

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 50-dBA maximum sound pressure level

Environmental Operating temperature 50° to 122° F (10° to 50° C)

Non-operating

-22° to 140° F (-30° to 60° C)

temperature

Operating humidity 10% to 90% (non-condensing at ambient) Non-operating humidity20% to 80% (non-condensing at ambient)

Operating shock 40g, six surfaces Non-operating shock 80g, six surfaces Operating vibration 2-g peak acceleration Non-operating 4-g peak acceleration

vibration

Drop (out of box) 30 in (76 cm) on carpet, 5-drop sequence **Drop** (in box) 30 in (76 cm) on rigid surface, 10-drop

sequence

ULcUL, FCC, CE, TUV/Bauart, VCCI, BSMI, C-Tick, KCC **Approvals**

Ergonomic compliance N/A



Technical Specifications - Input Devices

HP USB Mini-Keyboard Physical Keys 87, 88, 89, 91 layout (depending upon

characteristics country)

Dimensions (L x W x H) 14.76 x 6.73 x 0.96 in (374.90 x 170.94 x

24.38 mm)

Weight 2 lb (0.9 kg) minimum

Electrical Operating voltage + 5VDC ±5%

Power consumption 100-mA maximum (with three LEDs ON)

System interface
USB Type A plug connector
CE level 4, 15-kV air discharge
Conforms to FCC rules for a Class B

computing device

computing device

Microsoft PC 99 – 2001 Functionally compliant

MechanicalLanguagesCurrently 7 available

Keycaps Stepped -profile design

Switch actuation 55-g nominal peak force with tactile feedback **Switch life** 20 million keystrokes (using Hasco modified

tester)

Switch type Contamination-resistant switch membrane **Key-leveling** For all double-wide and greater-length keys

mechanisms

Cable length 6 ft (1.8 m)

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Environmental Operating temperature 50° to 122° F (10° to 50° C)

Non-operating -22° to 140° F $(-30^{\circ}$ to 60° C)

temperature

Operating humidity 10% to 90% (non-condensing at ambient) **Non-operating humidity**20% to 80% (non-condensing at ambient)

Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesOperating vibration2-g peak accelerationNon-operating4-g peak acceleration

vibration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 42 in (107 cm) on concrete, 16-drop

sequence

Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC,

USB-IF

Ergonomic compliance ANSI HFS 100, ISO 9241-4, and TUVGS



Technical Specifications - Input Devices

Compaq USB 2-Button Scroll Wheel **Optical Scroll Mouse**

24

Maximum Rotation

Speed

Electrical

Mechanical

48 rats/sec

Switch Type wheel

Switch Life Button - 1.000.000

Wheel - 200,000 times

Environmental Operating Temperature 32° to 104° F (0° to 40° C)

Non-operating

-4° to 140° F (-20° to 60° C)

Temperature

Operating Humidity 10% to 90% (non-condensing at ambient) Non-operating 20% to 80% (non-condensing at ambient)

Humidity

Operating Shock 40 g, six surfaces **Non-operating Shock** 80 g, six surfaces **Operating Vibration** 2-g peak acceleration Non-operating 4-g peak acceleration

Vibration

Switch Life

Operating Voltage 4.35V-5.25V DC

> **Power Consumption** <100mA **MTBF** > 150,000 hrs

ESD IEC-61000-4-2 criteria B, Contact discharge:

+/- 4kV, Air discharge: +/- 8kV

EMI-RFI FCC Class B **PC98** PC 99 Compliant 500±10% DPI Resolution

Tracking Speed 25 cm/sec Acceleration 0.5mm **Switch Actuation** 0.6N (60gf)

> Button - 1,000,000 Wheel - 200,000 times

Cable Length 1.8m

PC98-99 PC99 compliant

Regulatory Approvals ULcUL, FCC, CE, TUV/GS, VCCI, BSMI, C-Tick, MIC



Technical Specifications - Hard Drives

Serial ATA Hard Drives 160 GB

(7200 rpm)

Capacity 160,041,885,696 bytes

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer 3.0 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm Logical Blocks 312,581,808

Operating Temperature32° to 140° F (0° to 60° C)

250 GB Capacity 250,059,350,016 bytes

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer 3.0 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm **Logical Blocks** 488,397,168

Operating Temperature41° to 131° F (5° to 55° C)

320 GB Capacity 320,072,933,376 bytes

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.9 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer Up to 3 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm Logical Blocks 625,142,448

Operating Temperature41° to 131° F (5° to 55° C)

500 GB Capacity 500,107,862,016 bytes



Technical Specifications - Hard Drives

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer 3.0 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature41° to 131° F (5° to 55° C)



Write

QuickSpecs

Technical Specifications - Optical Storage

SATA DVD-ROM Drive Height 5.25-inch, half-height, tray-load

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc capacity Single layer: Up to 4.7 GB (6 times capacity of CD-ROM)

Double layer: Up to 8.5 GB (12 times capacity of CD-ROM)

Dimensions (W x H x D) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

Weight (max) 2.6 lb (1.2 kg)

Read speeds DVD+R/-R/+RW/ Up to 8X

Media

-RW/+R DL /-R DL

DVD-ROM Up to 16X
DVD-RAM Up to 4X
CD-ROM, CD-R Up to 48X
CD-RW Up to 32X

Removable Storage - Media Compatibility -

DVD-ROM

Yes **CD-ROM** No CD-R Yes No CD-RW Yes No **DVD-ROM** Yes No **DVD-ROM DL** Yes No Yes **DVD-RAM** No DVD+R Yes No DVD+R DL Yes Nο **DVD+RW** Yes No DVD-R Yes No **DVD-RW** Yes Nο **DVD-R DL** Yes No

Read

Access times

(typical reads, including

setting)

Random DVD: < 140 ms (typical), CD: < 125 ms

(typical)

Full Stroke DVD: < 250 ms (seek), CD: < 210 ms (seek)

Cache Buffer 2 MB (minimum)

Data Transfer Modes ATA PIO mode 4 (16.7 MB/s); ATA Multi-word

DMA mode 2 (16.7 MB/s); ATA UltraDMA

Mode 3 (44.4 MB/s -default)

Power Source SATA DC power receptacle

DC Power Requirement5 VDC ± 5%-100 mV ripple p-p

12 VDC ± 5%-200 mV ripple p-p

DC Current 5 VDC - <1000 mA typical, < 1600 mA

maximum

12 VDC -< 600 mA typical, < 1400 mA

maximum

Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-condensing)

Relative Humidity 10% to 90%

Maximum Wet Bulb 86° F (30° C)

Temperature

remperature



Technical Specifications - Optical Storage

HP SATA SuperMulti Height 5.25-inch, half-height, tray-load LightScribe DVD Writer Orientation Either horizontal or vertical

Drive

Interface type SATA/ATAPI Disc capacity 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

Weight (max) 2.6 lb (1.2 kg)

Write speeds **DVD-RAM** Up to 12X

> DVD+R Up to 16X **DVD+RW** Up to 8X DVD+R DL Up to 8X **DVD-R DL** Up to 8X DVD-R Up to 16X **DVD-RW** Up to 6X CD-R Up to 48X CD-RW Up to 32X

Read speeds **DVD-RAM** Up to 12X

DVD+R/-R/+RW/ Up to 8X

-RW/+R DL /-R DL

DVD-ROM DL Up to 8X DVD-ROM, DVD+R, Up to 16X

DVD-R

Full Stroke

CD-ROM, CD-R Up to 48X CD-RW Up to 32X

Access times

(typical reads, including

setting)

Random DVD: < 140 ms (typical), CD: < 125 ms

(typical)

DVD: < 250 ms (seek), CD: < 210 ms (seek) Power Source SATA DC power receptacle

DC Power Requirement5 VDC ± 5%-100 mV ripple p-p

12 VDC ± 5%-200 mV ripple p-p

DC Current 5 VDC - <1000 mA typical, < 1600 mA

maximum

12 VDC -< 600 mA typical, < 1400 mA

maximum

Environmental 41° to 122° F (5° to 50° C) **Temperature**

(all conditions **Relative Humidity** 10% to 90% non-condensing) **Maximum Wet Bulb** 86° F (30° C)

Temperature

Technical Specifications - Miscellaneous

HP FireWire/IEEE 1394a PCI Card

Data Transfer Rate Burst Data Rate up to 400 Mb/s

Device Interface IEEE-1394a

Protocol

Devices Supported IEEE-1394 compliant devices

Bus Type PCI card with brackets for low profile and full height PCI slots.

Certification Level FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-

1998 STD, Taiwan BSMI CNS13438, Korea MIC

Ports Two IEEE 1394 6-Pin Connector (Rear)
Internal Connectors One 10-Pin (9 Contacts) Custom Connector

Temperature – 50° to 131° F (10° to 55° C)

Operating

Temperature – Storage –22° to 140° F (–30° to 60° C)

Relative Humidity – 20% to 80%

Operating

Technical Specifications - Environmental Data

Eco-Label Certifications and declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

IT ECO declaration

System Configuration The configuration used for the Energy Consumption and Declared Noise Emissions data for the Microtower model is based on a typically configured product.

Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	54.478W	54.023W	53.460W
Sleep (Energy Star low power mode)	1.588W	1.732W	1.524W
Off	1.015W	1.021W	0.964W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	186 BTU/hr	185 BTU/hr	183 BTU/hr
Sleep	5 BTU/hr	6 BTU/hr	5 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr

^{*} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise

Emissions

(in accordance with ISO 7779 and ISO 9296)

	Sound Power	Sound Pressure
System Fan Off	(LWAd, bels)	(LpAm, decibels)
Idle	3.7	25.4
Fixed Disk (random writes)	3.8	28.1

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Li Ion

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0% post consumer recycled plastic (by wt.)
- This product is 93.1% recyclable when properly disposed of at end of life.

Packaging Materials External

Corrugated 1680 g Internal **EPE-Expanded Polyethylene** 115 g Polyethylene low density foam 40 g

- The EPE-Expanded Polyethylene packaging material is made from 0% recycled content.
- The Polyethylene low density foam packaging material is made from 0% recycled content.
- The Corrugated packaging materials contains at least 0% recycled content.



Technical Specifications - Environmental Data

RoHS Compliance

Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the

Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Hewlett-Packard Corporate

For more information about HP's commitment to the environment: Global Citizenship Report



Technical Specifications - Environmental Data

Environmental Information

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

Copyright © 2009 Hewlett-Packard Development Company, L.P.

All rights reserved. Microsoft, Windows, Windows 7, and Windows Vista are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Core 2 Quad, Core 2 Duo, Pentium and Celeron are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a registered trademark of Bluetooth SIG, Inc., in the U.S. and other countries. All other product names mentioned herein may be trademarks of their respective companies.

The information contained herein is subject to change without notice and is provided "as is" without warranty of any kind. The warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

